ABSTRACT

APPARATUS AND METHOD FOR DIE ATTACHMENT

The invention provides an apparatus for die attachment onto a substrate including non-metallic material, and metallic material that is adapted to receive a die having a eutectic coating. A heating conduit is provided through which the substrate is movable for heating the metallic material to a eutectic bonding temperature to facilitate bonding between the die and the metallic material at a die-attach position. An induction heating device at the die-attach position heats the metallic material of the substrate to the eutectic bonding temperature prior to attaching a die onto the metallic material.

(Figure 5)